



SOT1747-2

HSOP54, plastic, heatsink small outline package; W/B, tooth gap design, 54 terminals; 0.65 mm pitch; 4.6 mm x 10.4 mm exposed pad

15 January 2021

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP54
Package type industry code	HSOP54
Package style descriptive code	HSOP (heatsink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-01-2021
Manufacturer package code	98ASA00367D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.4	7.5	7.6	mm
package width	17.8	17.9	18	mm
seated height	2.22	2.34	2.45	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	54	-	



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2 Package outline

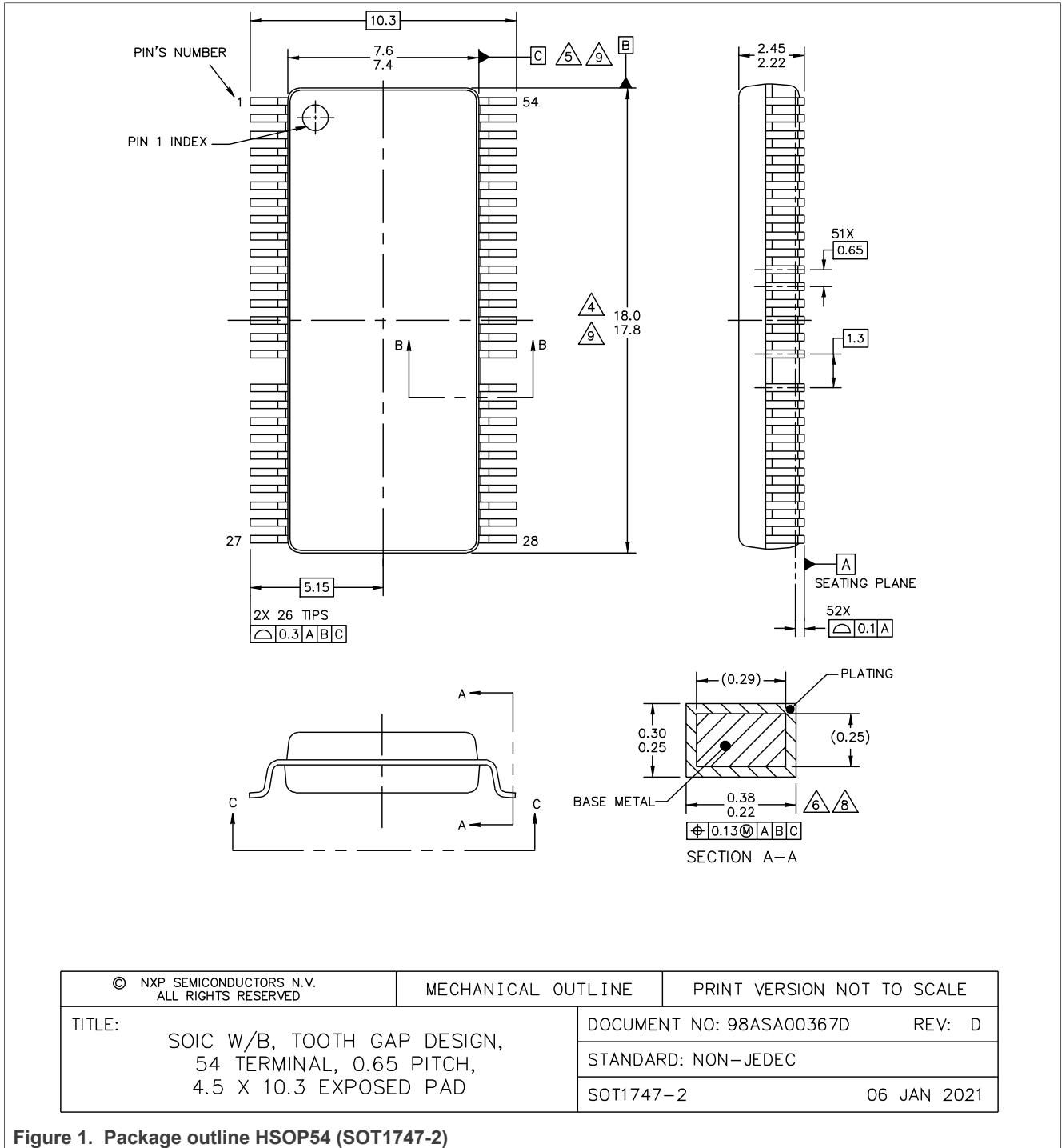
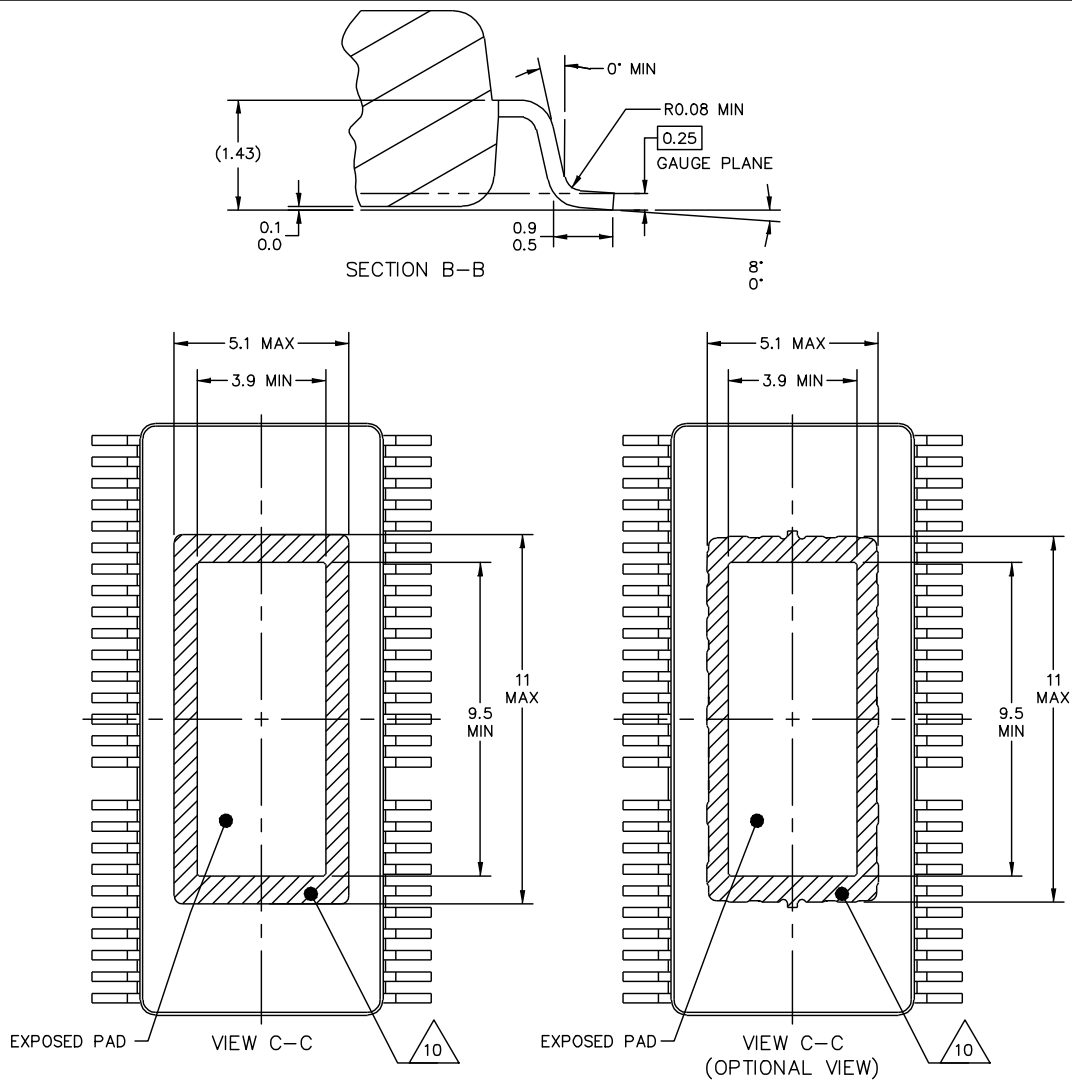


Figure 1. Package outline HSOP54 (SOT1747-2)

HSOP54, plastic, heatsink small outline package; W/B, tooth gap design, 54 terminals; 0.65 mm pitch; 4.6 mm x 10.4 mm exposed pad



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TITLE: SOIC W/B, TOOTH GAP DESIGN, 54 TERMINAL, 0.65 PITCH, 4.5 X 10.3 EXPOSED PAD	DOCUMENT NO: 98ASA00367D	REV: D
	STANDARD: NON-JEDEC	
	SOT1747-2	06 JAN 2021

Figure 2. Package outline dt HSOP54 (SOT1747-2)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 mm.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 mm AND 0.3 mm FROM THE LEAD TIP.
9. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
10. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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Figure 3. Package outline note HSOP54 (SOT1747-2)

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3 Legal information

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